

Breakdown of component	Material Name	Substance Name	CAS No.	Substance Mass		Material Mass (wt%)
				(mg)	(wt%)	
Lid	Kovar Lid	Nickel (Ni)	7440-02-0	1.37100	30.0	4.4509
		Cobalt (Co)	7440-48-4	0.79975	17.5	2.5963
		Iron (Fe)	7439-89-6	2.39925	52.5	7.7890
Blank	Crystal Blank	Silicon dioxide (SiO2)	14808-60-7	0.89773	99.97	2.9144
		Aluminum oxide (Al2O3)	1344-28-1	0.00013	0.014	0.0004
		Ferric oxide (Fe2O3)	1309-37-1	0.00014	0.016	0.0005
Base	Ceramic	Aluminum oxide (Al2O3)	1344-28-1	13.1855	90.0	42.8060
		Silicon oxide (SiO2)	7631-86-9	0.8790	6.0	2.8537
		Chromium oxide (Cr2O3)	1308-38-9	0.2930	2.0	0.9512
		Molybdenum (Mo)	7439-98-7	0.2930	2.0	0.9512
	Metallizing	Tungsten (W)	7440-33-7	3.9762	100.0	12.9085
	Seal ring	Iron (Fe)	7439-89-6	2.4437	53.0	7.9332
		Nickel (Ni)	7440-02-0	1.3371	29.0	4.3408
		Cobalt (Co)	7440-48-4	0.8299	18.0	2.6943
	Solder	Silver (Ag)	7440-22-4	0.8729	71.0	2.8340
		Copper (Cu)	7440-50-8	0.3566	29.0	1.1575
	Ni Plate	Nickel (Ni)	7440-02-0	0.0615	100.0	0.1997
	Au Plate	Gold (Au)	7440-57-5	0.0615	100.0	0.1997
IC	Wafer	Silicon(Si)	7440-21-3	0.2627	100.0	0.8529
	D/B adhesive	Silanamine, 1,1,1-trimethyl-N-(trimethylsilyl)-, hydrolysis products with silica	68909-20-6	0.1855	40.0	0.6021
		Fatty acids, C18-unsatd., dimers, hydrogenated, di-Me esters, hydrogenated, bis(2,5-dihydro-2,5-dioxo-1H-pyrrole-1-hexanoate)	NA	0.1391	30.0	0.4516
		Filler	Trade Secret	0.0695	15.0	0.2258
		Acrylate monomer	Trade Secret	0.0232	5.0	0.0753
		Epoxy resin	Trade Secret	0.0232	5.0	0.0753
		Additive	Trade Secret	0.0232	5.0	0.0753
	Au wire	Gold(Au)	7440-57-5	0.0091	100.0	0.0294
Adhesive	DOTITE	Silver (Ag)	7440-22-4	0.000267	76.3	0.0009
		Silicone Resin	NA	0.000051	14.6	0.00017
		n-Dodecane (C12H26)	112-40-3	0.000029	8.3	0.00009
		Alkoxysilane (C11H22O4Si)	3388-04-3	0.000003	0.8	0.00001
Electrode	Ag	Silver (Ag)	7440-22-4	0.00924	100.0	0.0300
<b>TOTAL</b>				<b>30.8030</b>		<b>100.0000</b>